

# Memory Module Specification

## KHX1800C8D3/1G

## 1GB 128M x 64-Bit DDR3-1800MHz CL8 240-Pin DIMM

### **DESCRIPTION:**

This document desribes Kingston's 128M x 64-bit 1GB (1024MB) DDR3-1800MHz CL8 SDRAM (Synchronous DRAM) memory module, based on eight 128M x 8-bit DDR3 FBGA components. This module has been tested to run at DDR3-1800MHz at a low latency timing of 8-8-8-24 at 1.7V to 1.9V. The SPD is programmed to JEDEC standard latency DDR3-1333MHz timing of 9-9-9 at 1.5V. Each 240-pin DIMM uses gold contact fingers and requires +1.5V. The JEDEC standard electrical and mechanical specifications are as follows:

#### **FEATURES:**

✓ JEDEC standard  $1.5V \pm 0.075V$  Power Supply

 $\forall$  VDDQ = 1.5V ± 0.075V

✓ 667MHz fCK for 1333Mb/sec/pin

8 independent internal bank

Programmable CAS Latency: 5,6,7,8,9,10

Posted CAS

Programmable Additive Latency: 0, CL - 2, or CL - 1 clock

Programmable CAS Write Latency(CWL) = 7(DDR3-1333)

8-bit pre-fetch

Burst Length: 8 (Interleave without any limit, sequential with starting address "000" only), 4 with tCCD = 4 which does not allow seamless read or write [either on the fly using A12 or MRS]

Bi-directional Differential Data Strobe

✓ Internal(self) calibration : Internal self calibration through ZQ pin (RZQ : 240 ohm ± 1%)

On Die Termination using ODT pin

Average Refresh Period 7.8us at lower then TCASE 85°C, 3.9us at 85°C < TCASE . 95°C

Asynchronous Reset

PCB: Height 1.180" (30.00mm), single sided component

### PERFORMANCE:

CL(IDD)
9 cycles
Row Cycle Time (tRCmin)
49.5ns (min.)
Refresh to Active/Refresh Command Time (tRFCmin)
110ns
Row Active Time (tRASmin)
36ns (min.)
Power
1.080 W
UL Rating
94 V - 0
Operating Temperature
0° C to 85° C

✓ Storage Temperature -55° C to +100° C

## **MODULE DIMENSIONS:**





